



3K1500 thermal conductive silicon pad

3K1500 thermal conductive silicon pad is high-performance thermal conductive gap filling materials, mainly for the transmission interface between the electronic equipment and heat sink or product outer coving. Nice stickiness, flexibility, good compression performance and excellent heat conductivity are designed for 3K1500series, which make the products can discharge gas from the electronic original and heat sink, to achieve fully conforming and obviously cooling effect. Compared to common thermal conductive & insulating materials, 3k1500 series has certain



in the product installation processing, not easy to fall off and easy to operate.

Features & benefits:

- High reliability & High thermal conductivity
- High compressibility, soft and flexible
- Natural stickiness, no extra surface frontal adhesives
- Meet with the environmental requirements of ROHS and UL

Typical applications:

- Communication equipment
- LED Light
- Switching power supply
- Back light model
- Medical equipment
- Mobile equipment
- Video equipment
- Networking equipment
- Household appliances
- PC server/workstations

Application modes:

- The filling between PCB and heat sink
- The filling between IC and heat sink or product outer coving
- The filling between IC and similar heatsink cooling materials

Test item	Test method	Unit	3K1500Test Value
Color	Visual		Blue/grey/custom
Thickness	ASTM D374	Mm	0.5 to20.0
Specific Gravity	ASTM D792	g/cm ³	3.2±0.1
Hardness	ASTM D2240	Shore C	35
Tensile Strength	ASTM D412	kg/cm ²	12
	ASTM D412	Pa	5.8*10 ⁹
Continuous Use Temp	EN344	°C	-40 to +250
Volume Resistivity	ASTM D257	Ω-CM	2.9*10 ¹¹
Breakdown Voltage	ASTM D149	KV/mm	>10
Flame Rating	UL-94		V-0
Conductivity	ASTM D5470	w/m-k	15